## OUTLINES DIMENSIONS



Notes:

1. All Dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25 \mathrm{~mm}$ ( $0.01^{\prime \prime}$ ) unless otherwise noted.

3 . Specifications are subject to change without notice.

| Part Number | Chip Material | Color of Emission | Lens Type | Description |
| :---: | :---: | :---: | :---: | :---: |
| CDSAP28B2WBF | InGaN | Blue | White Segment | Common Anode |


| Parameter | Symbol | Max Rating | Unit |
| :--- | :---: | :---: | :---: |
| Power Dissipation | Pd | 80 | mW |
| Pulse Forward Current | IFP | 120 | mA |
| Continuous Forward Current | IF | 20 | mA |
| Reverse Voltage Segment | VR | 5 | V |
| Operating Temperature Range | ToPR | $-25 \sim+85$ | ${ }^{\circ} \mathrm{C}$ |
| Storage Temperature Range | TsTG | $-30 \sim+85$ | ${ }^{\circ} \mathrm{C}$ |
| IFP = Pulse Width $\leq 10 \mathrm{~ms}$, Duty Ratio $\leq 1 / 10$. Soldering Condition: $260{ }^{\circ} \mathrm{C} / 5 \mathrm{sec}$ |  |  |  |

## OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25 ${ }^{\circ} \mathrm{C}$ )

| Parameter | Symbol | Test Condition | Value |  |  |  |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | Min | Typ | Max |  |
| Luminous Intensity | $I_{V}$ | $I_{F}=10 \mathrm{~mA}$ | 26 | 70 | - | mcd |
| Forward Voltage | $\mathrm{VF}_{\mathrm{F}}$ | $\mathrm{IF}_{\mathrm{F}}=20 \mathrm{~mA}$ | - | 3.2 | 3.5 | V |
| Reverse Leakage Current | IR | $\mathrm{V}_{\mathrm{R}}=5 \mathrm{~V}$ | - | - | 20 | $\mu \mathrm{~A}$ |
| Dominant Wavelength | $\lambda \mathrm{D}$ | $\mathrm{I}_{\mathrm{F}}=20 \mathrm{~mA}$ | - | 460 | - | nm |
| Spectral Radiation Bandwidth | $\Delta \lambda$ | $\mathrm{I}_{\mathrm{F}}=20 \mathrm{~mA}$ | - | 30 | - | nm |

## OPTICAL CHARACTERISTIC CURVES







## - RECOMMEND SOLDERING PROFILE



## - SOLDERING IRON

Basic spec is $\leqq 4$ sec when $260^{\circ} \mathrm{C}$. If temperature is higher, time should be shorter ( $+10^{\circ} \mathrm{C} \rightarrow 1 \mathrm{sec}$ ). Power dissipation of Iron should be smaller than 15 W , and temperature should be controllable. Surface temperature of the device should be under $230^{\circ} \mathrm{C}$.

## - REWORK

Customer must finish rework within $\leqq 4$ sec under $245^{\circ} \mathrm{C}$.

